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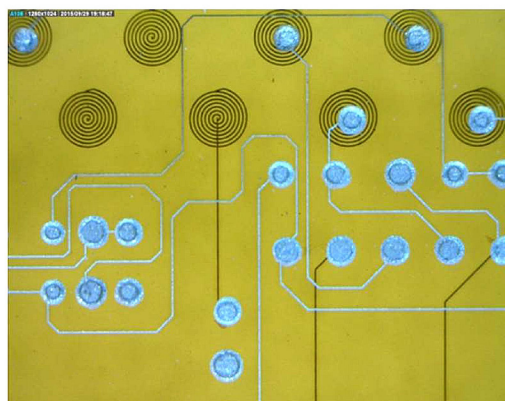
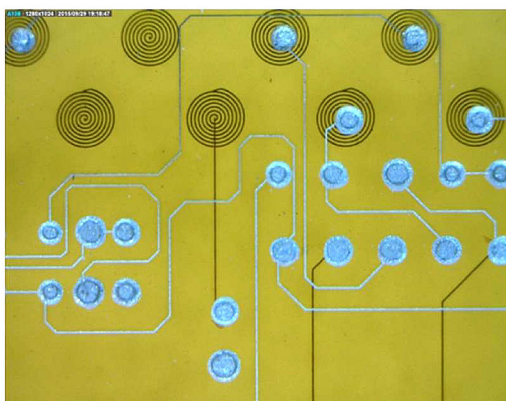
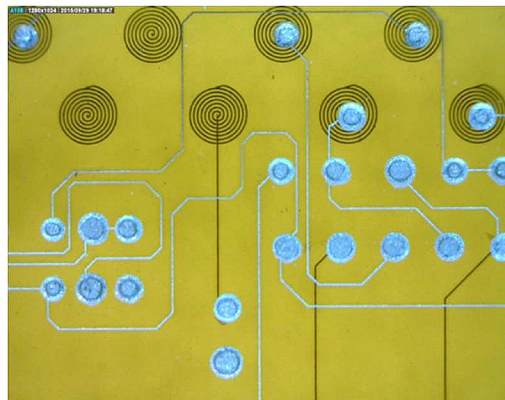
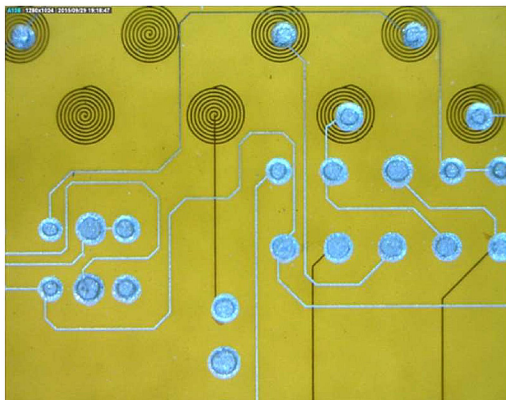
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Cover art from: "Integration of Miniature Electronic Assemblies Using Nanoparticle Silver Conductors, Polymer Bump Connections, and Encapsulated Component Blocks" by C. Paul Christensen and Natalya Christensen (p. 527–532, Fig. 5).



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